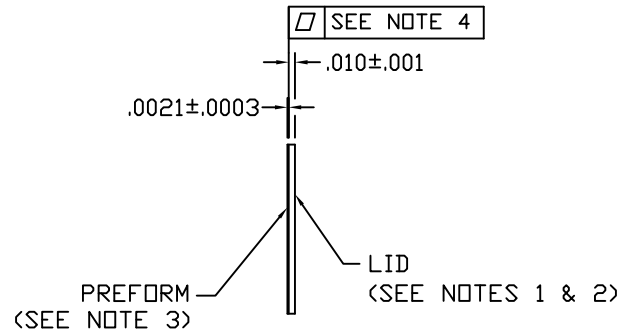
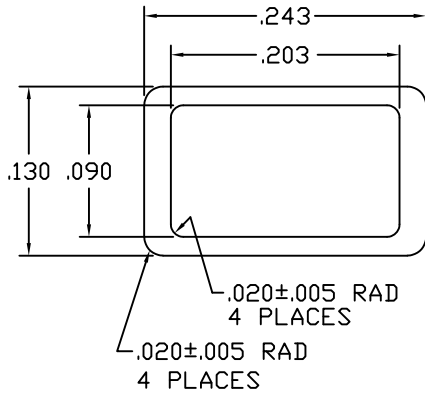


SSM P/N CL241302



NOTES

1. MAT'L : KOVAR OR ALLOY 42
 2. PLATING : 1st LAYER 50/350 MICROINCHES Ni
2nd LAYER 25 MICROINCHES MIN Au
3rd LAYER 50/350 MICROINCHES Ni
4th LAYER 25 MICROINCHES MIN Au
- NOTES : TOTAL NICKEL LAYERS SHALL NOT EXCEED 450 MICROINCHES AND THE SUM OF BOTH GOLD LAYERS SHALL BE 50 MICROINCHES MINIMUM.
3. PREFORM - 80% ±1% Au
20% Sn
 4. FLATNESS : ONE MIL (.001) MAXIMUM PER 1/2" T.I.R
 5. TOLERANCES TO BE (XXX) 3 PLACES ±.003 UNLESS OTHERWISE NOTED

DESCRIPTION		Hi-Rel Combo Lid	
PART NAME		CL241302	
Spectrum Semiconductor Materials, Inc. 155 Nicholson Lane San Jose, CA 95134 PH: (408) 435-5555 Fx: (408)435-8226		MFG: Williams Advanced Materials, Inc.	
		PART No.	HRC-862-21-25MT-100MNI-S

